


**DS - 01/03/2006 ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18


Stylesheet Version v18.0

<b>Title of Invention</b>	<b>Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking</b>						
<p>Application Number : 10/050507 </p> <p>Confirmation Number: 7687</p> <p>First Named Applicant: Teck Lee</p> <p>Attorney Docket Number: MTI-31607</p> <p>Art Unit: 2813</p> <p>Examiner: Jack SJ Chen</p> <p>Search string. ( 6624060 or 20020027080 or 20030134450 ).pn</p>							
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DAZ	1	6624060	2003-09-23	Chen et al.		438	613
<b>US Published Applications</b>							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
DAZ	1	20020027080	2002-03-07	Yoshioka et al.	A1	205	123
DAZ	2	20030134450	2003-07-17	Lee	A1	438	106
<b>Signature</b>							
Examiner Name				Date			
/David Zarneke/				05/22/2006			

**IDS - 11/10/2005 ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

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<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DAZ	1	6308525	2001-03-27	Imasu et al.		361	783
DAZ	2	5468995	1995-11-21	Higgins III		257	697
DAZ	3	6610559	2003-08-26	Wang et al.		438	108
<b>Signature</b>							
<b>Examiner Name</b>				<b>Date</b>			
/David Zarneke/				05/22/2006			

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Confirmation Number:		7687					
First Named Applicant:		Teck Lee					
Attorney Docket Number:		MTI-31607					
Art Unit:		2813					
Examiner:		Jack SJ Chen					
Search string:		( 4415403 or 6847105 ).pn					
 <b>US Patent Documents</b>							
<b>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</b>							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DAZ	1	4415403	1983-11-15	Bakewell		216	27
DAZ	2	6847105	2005-01-25	Koopmans		257	686
 <b>Signature</b>							
<b>Examiner Name</b>				<b>Date</b>			
/David Zarneke/				05/22/2006			